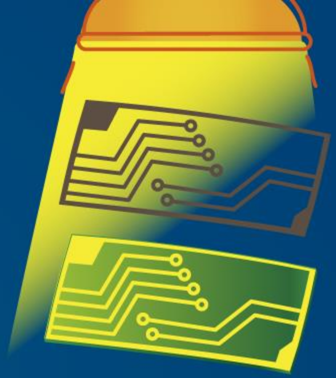
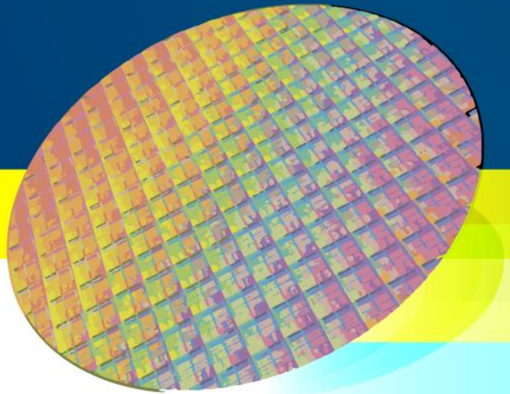
c sun

志聖法人說明會 2467.TT

Investor Conference





Morrison Liang, Chairman
Jamie Wu, Co-head
Kent Chen , Co-head

Venue: Taiwan Stock Exchange Taipei 101
October 27th , 2020

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Agenda

- **2020 Q3 Operating Results**
- **Growth Opportunities &Product Development**
- **Q&A**

2020Q3

Operating Results

2020 Q3 Operating Results

in TWD millions

	2020Q3累計		2019Q3累計		2019		2018		2017	
	Amount	%	Amount	%	Amount	%	Amount	%	Amount	%
Revenue-Consolidated	2,750		3,368		4,438		5,700		5,003	
COGS			2,384	70.8%	3,170	71.4%	3,902	68.5%	3,345	66.9%
Gross Margin			985	29.2%	1,268	28.6%	1,798	31.5%	1,658	33.1%
Operating Expense			756	22.4%	954	21.5%	1,119	19.6%	1,091	21.8%
Operating Income			229	6.8%	314	7.1%	679	11.9%	567	11.3%
Net Non-Op. Profit			143	4.2%	104	2.3%	106	1.9%	(53)	-1.1%
Net Income before tax			371	11.0%	418	9.4%	785	13.8%	514	10.3%
Net Income after tax			287	8.5%	338	7.6%	598	10.5%	427	8.5%
Attribute to stockholder's of the parent	299	10.9%	268	8.0%	312	7.0%	556	9.8%	403	8.1%
ROE	11.70%		10.00%		11.64%		21.83%		18.20%	
EPS (NT$/after tax)	$2.01		$1.80		$2.09		$3.73		$2.70	
Debt Ratio			59.50%		58.66%		58.23%		59.81%	

Growth Opportunities& Product Development

Growth Opportunities & Product Development

-G2C Alliance(C SUN、GPM、GMM)

Strategic Alliances for Competitive Advantage

-2019-2021 Operating Results Growth Opportunities :

· **Advanced Packaging(SEMI)** · **Flat Panel Display (FPD)**

· **Printed Circuit Board(PCB)**

2467 C SUN 志聖

tcF 創峰

5443 GPM 均豪

6640 GMM 均華

UTRON 祁昌

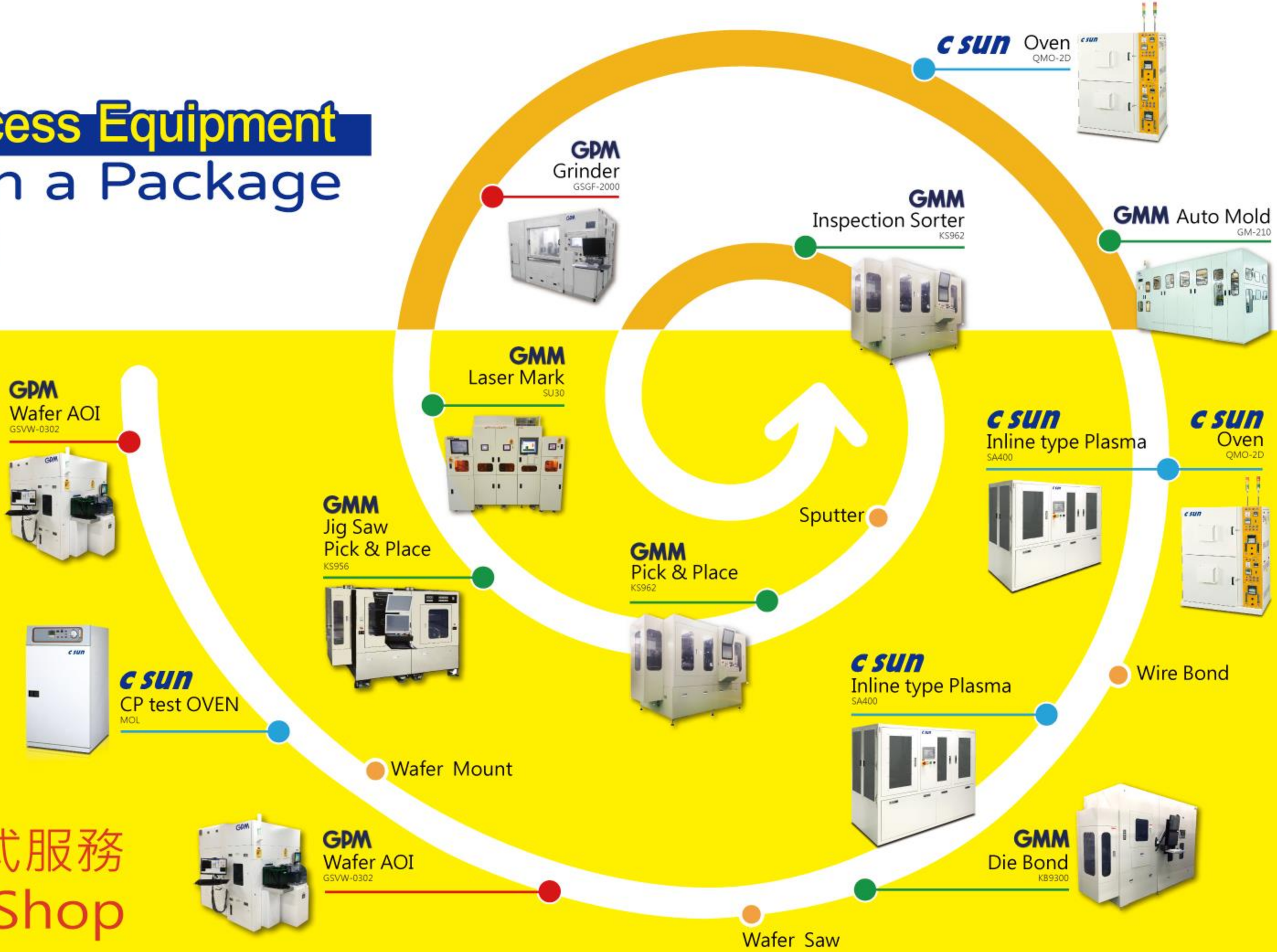
- The association among businesses in different industries
- Specialized in different area (Vertical Integration)
- Sufficient resources for all kinds of needs
- Members of the association **1,618**, RD members **529** (occupy **33%**)

合力共創 同行致遠 G2C Go Go Champion Great to Customers

SiP Process Equipment

System in a Package

系統級封裝



GPM Wafer AOI GSVW-0302

c sun CP test OVEN MOL

Wafer Mount

GPM Wafer AOI GSVW-0302

Wafer Saw

GMM Die Bond KB9300

c sun Inline type Plasma SA400

Wire Bond

c sun Inline type Plasma SA400

c sun Oven QMO-2D

GMM Auto Mold GM-210

c sun Oven QMO-2D

GPM Grinder GSGF-2000

GMM Laser Mark SU30

GMM Jig Saw Pick & Place KS956

GMM Pick & Place KS962

Sputter

GMM Inspection Sorter KS962

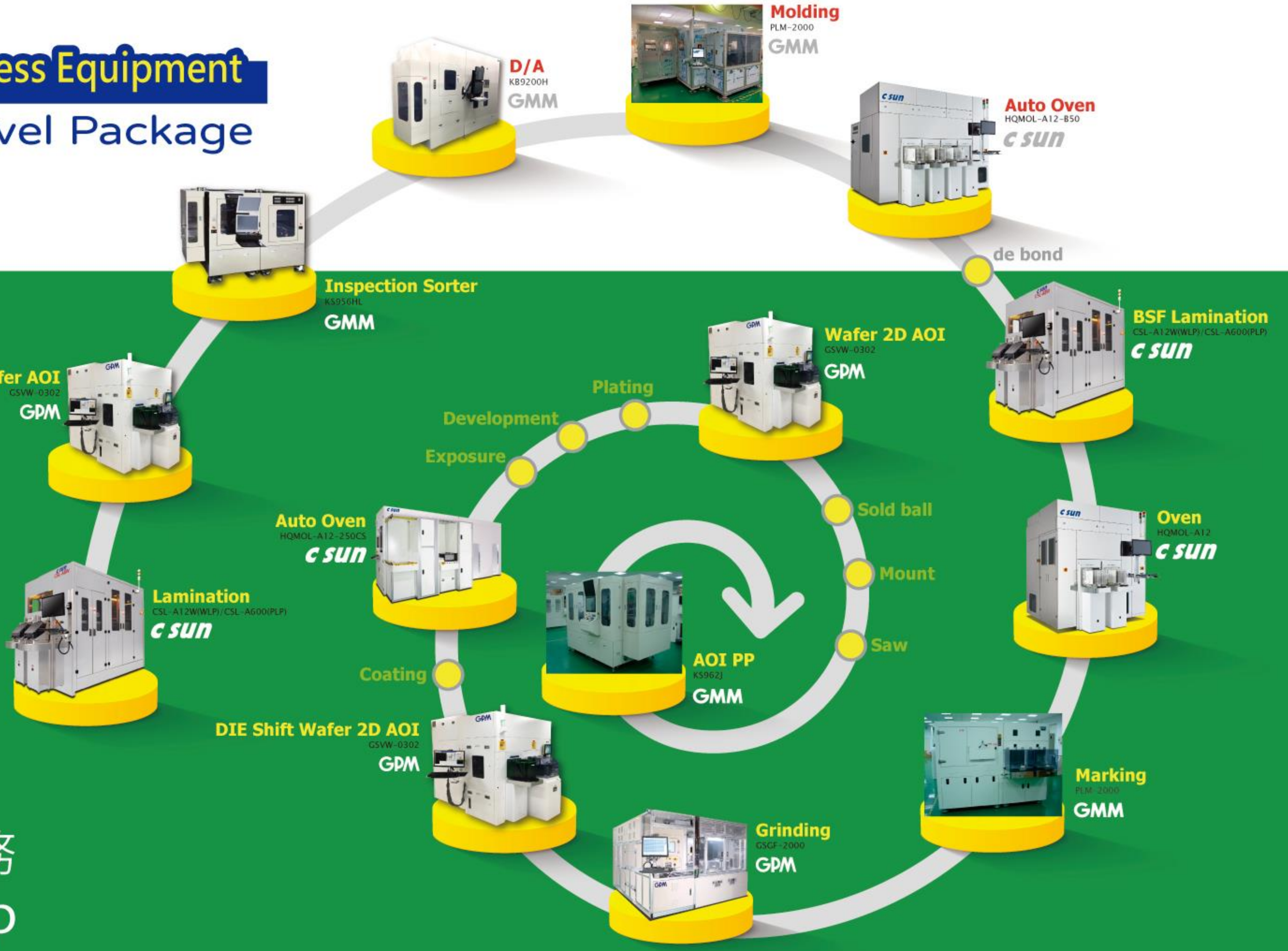
G2C 一站式服務

One Stop Shop

Fan Out Process Equipment

Fan Out Wafer Level Package

扇出型封裝



Lamination
CSL-A12W(WLP)/CSL-A600(PLP)
c sun

Wafer AOI
GSVW-0302
GPM

Inspection Sorter
KS956HL
GMM

D/A
KB9200H
GMM

Molding
PLM-2000
GMM

Auto Oven
HQMOL-A12-B50
c sun

de bond

BSF Lamination
CSL-A12W(WLP)/CSL-A600(PLP)
c sun

Oven
HQMOL-A12
c sun

Marking
PLM-2000
GMM

Grinding
GSGF-2000
GPM

DIE Shift Wafer 2D AOI
GSVW-0302
GPM

Coating

Auto Oven
HQMOL-A12-250CS
c sun

Exposure

Development

Plating

Wafer 2D AOI
GSVW-0302
GPM

Sold ball

Mount

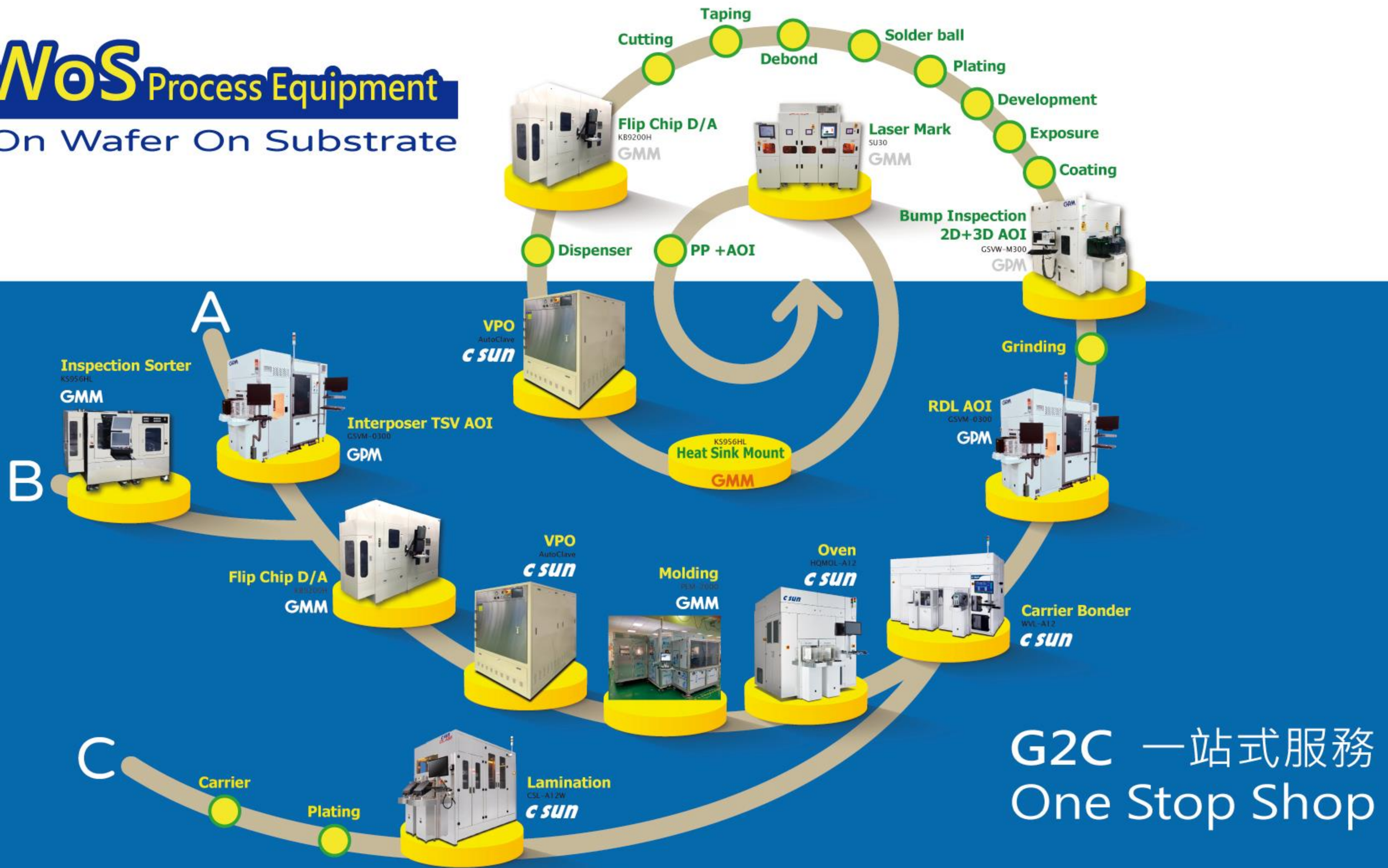
Saw

AOI PP
KS962J
GMM

G2C 一站式服務
One Stop Shop

CoWoS Process Equipment

Chip On Wafer On Substrate

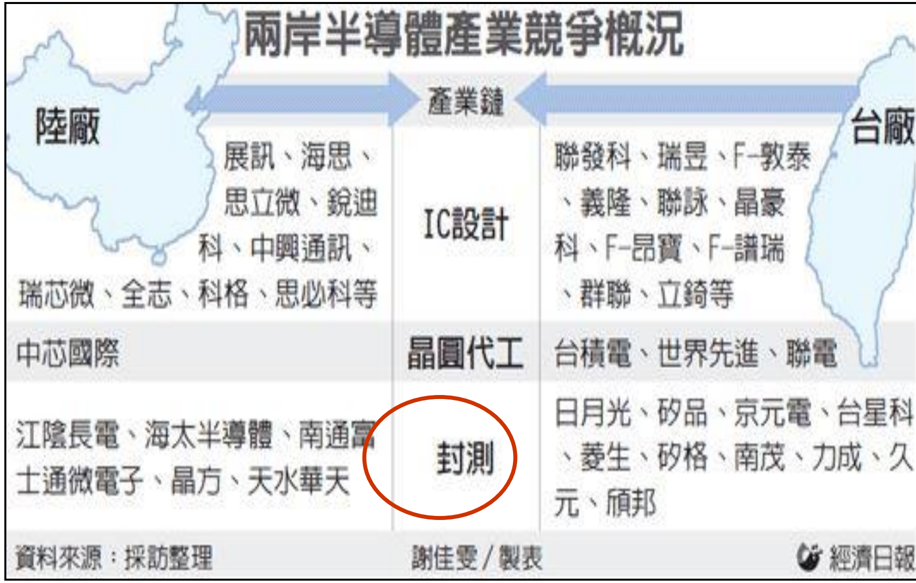


G2C 一站式服務
One Stop Shop

2020~2021 Growth Opportunities-
Semiconductor Field

Trend and market development

- Taiwan semiconductor supply Chains plays a key role in global semiconductor industry.
- U.S.-China trade war and COVID crisis accelerate the diversion of industry cluster and expedite the back to Taiwan investment.
- The trend of hereto-integration of technologies is undergoing and the growth of the advanced packaging sector is speeding up.
- CSUN and G2C alliance have manufacturing bases cross the Strait and ready to integrate for the new reality



兩岸半導體產業競爭概況

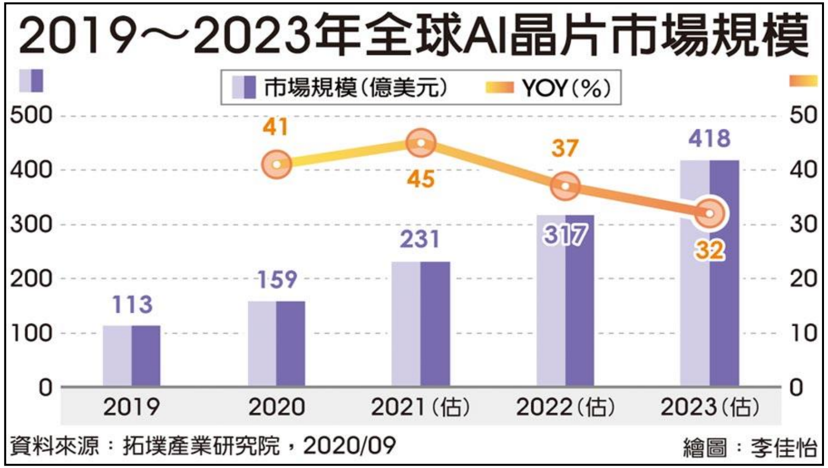
陸廠	產業鏈	台廠
展訊、海思、思立微、銳迪科、中興通訊、瑞芯微、全志、科格、思必科等	IC設計	聯發科、瑞昱、F-敦泰、義隆、聯詠、晶豪科、F-昂寶、F-譜瑞、群聯、立錡等
中芯國際	晶圓代工	台積電、世界先進、聯電
江陰長電、海太半導體、南通富士通微電子、晶方、天水華天	封測	日月光、矽品、京元電、台星科、菱生、矽格、南茂、力成、久元、頎邦

資料來源：採訪整理　謝佳雯／製表　經濟日報

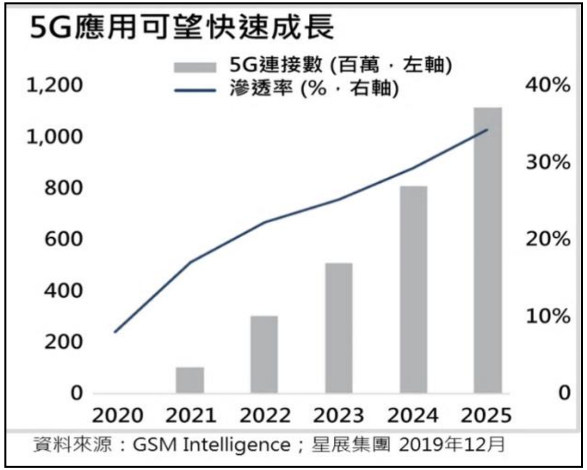
2020~2021 Growth Opportunities- Semiconductor Field

Trends/ market development

- The development of advanced packaging technologies spur the growth of 5G and AIoT silicons.
- The demand of silicons for 5G, AI and Autonomous cars is clear sky.
- COF packaging is in shortage as driver IC bumps into production bottlenecks.


2019～2023年全球AI晶片市場規模

資料來源：拓墣產業研究院，2020/09
繪圖：李佳怡


5G應用可望快速成長

資料來源：GSM Intelligence；星展集團 2019年12月

2020~2021 Growth Opportunities-Semiconductor Field

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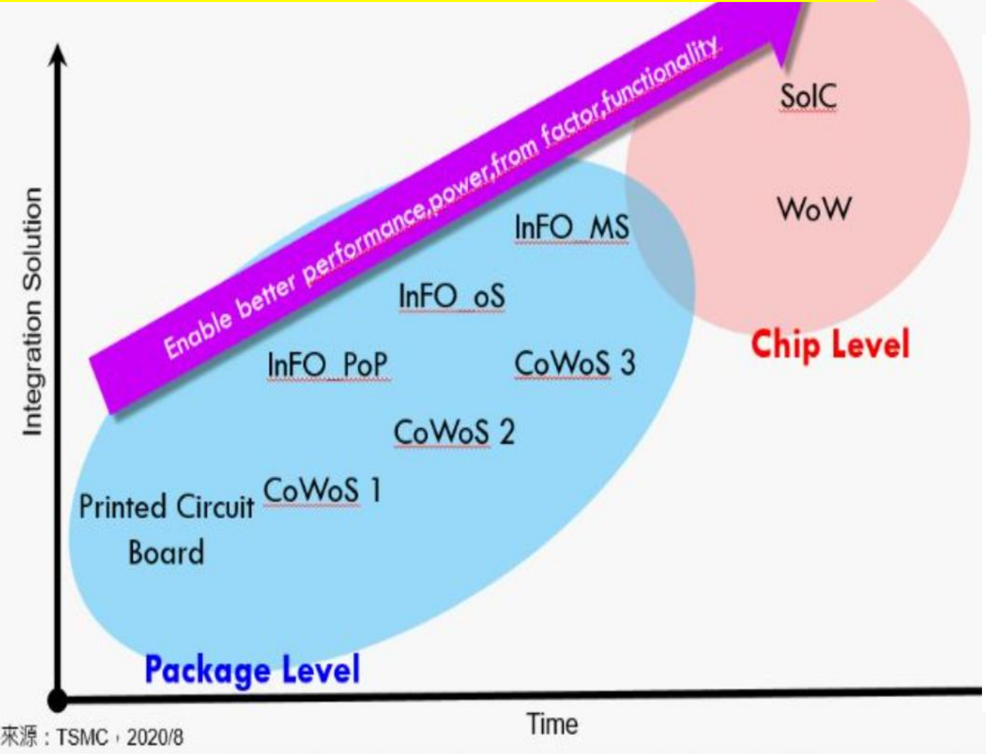
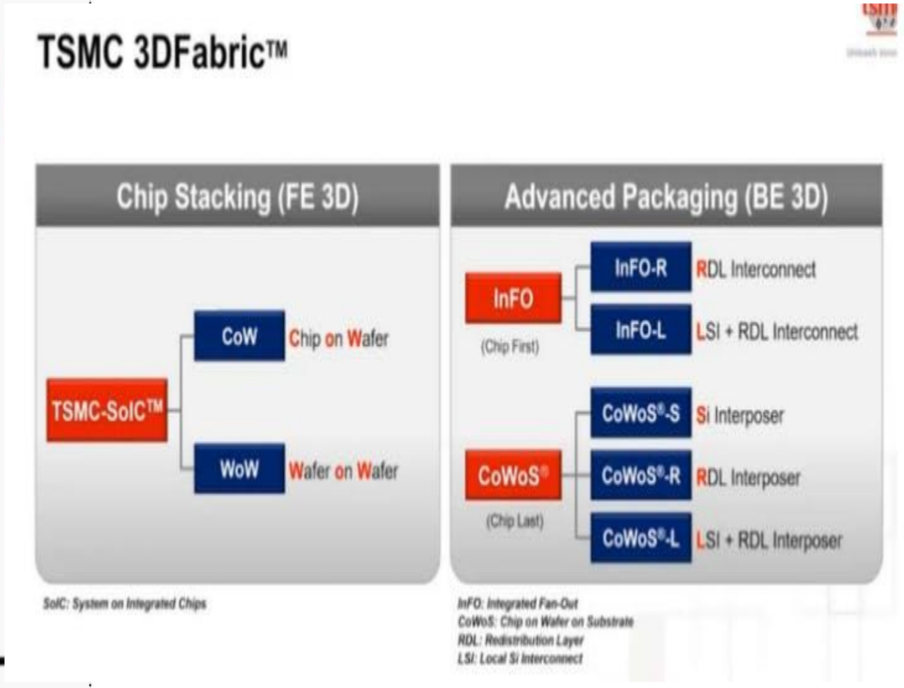
Advanced packaging technologies are moving to chip level – TSMC is the bellwether



資料來源：TSMC，2020/8



TSMC 3DFabric™

Chip Stacking (FE 3D)

- TSMC-SoIC™
  - CoW Chip on Wafer
  - WoW Wafer on Wafer

Advanced Packaging (BE 3D)

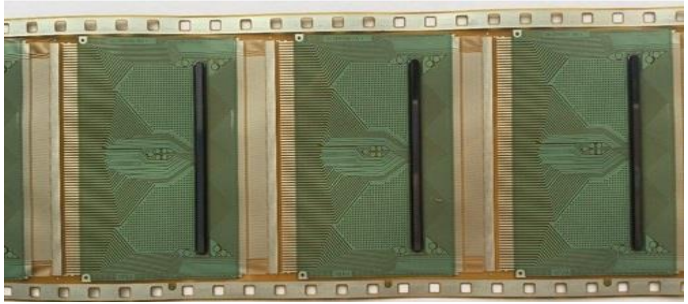
- InFO (Chip First)
  - InFO-R RDL Interconnect
  - InFO-L LSI + RDL Interconnect
- CoWoS® (Chip Last)
  - CoWoS®-S Si Interposer
  - CoWoS®-R RDL Interposer
  - CoWoS®-L LSI + RDL Interposer

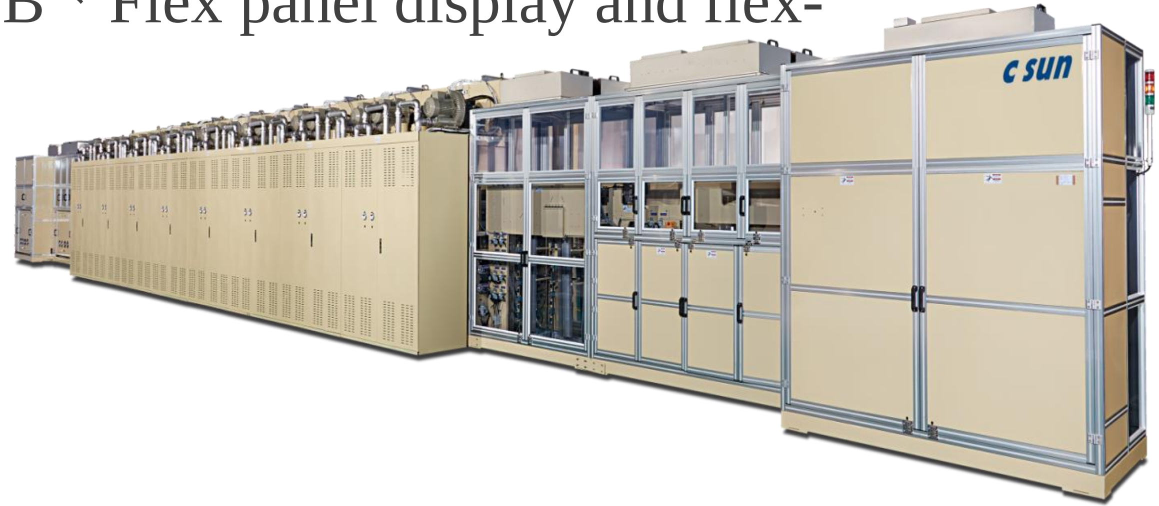
SoIC: System on Integrated Chips

InFO: Integrated Fan-Out
CoWoS: Chip on Wafer on Substrate
RDL: Redistribution Layer
LSI: Local Si Interconnect

Driver IC-COF R2R Oven

- Fully automated non contact type R2R oven has been moved in customer in China in Q1 2020 and repeat order is received.
- Applications: COF、FPCB、Flex panel display and flex-electronics.

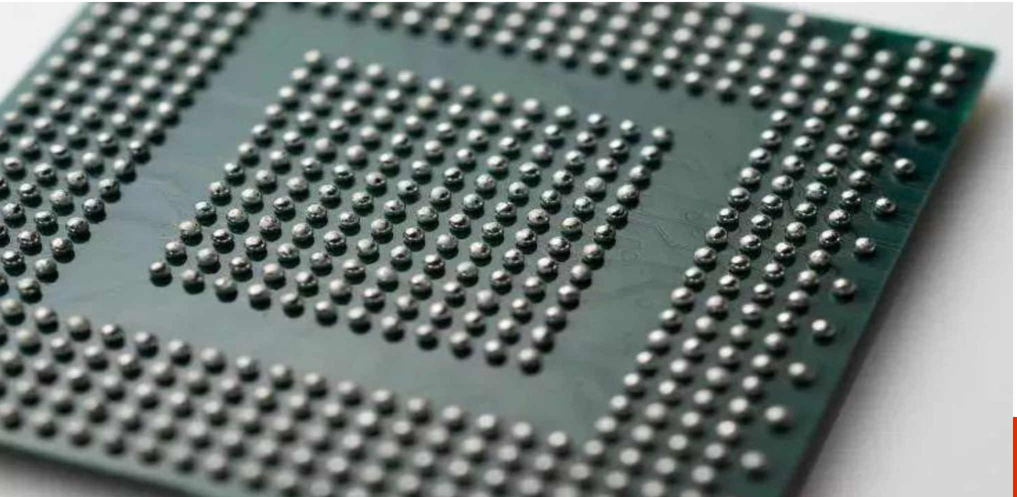




RTR Oven

Glue Dispensing Process—VPO

- For chip on wafer and u bump de-bubbling.
- Delivered to packaging big names.
- VPO connecting with OHT is certified by big name DRAM manufacturer in multi stacking process.



Vaccum/Pressure Oven

Growth Momentum in SEMI: 5G RF module

- RF modules integrated tread: Power Amplifier/filter integration

Wafer roller laminating machine

Fully auto wafer Mylar peeler

WLP / PLP Advanced Packaging Process

- Fan-Out RDL, The vacuum laminator of TSV, auto oven system
- Wafer vacuum laminator is preparing for mass production and repeat order to T-company, applied for SoW process
- Burn in Auto Oven had passed the test of China’s DRAM Packaging Fab, now we’re talking about new project

Wafer vacuum laminator

Burn in AUTO OVEN

AI & AIoT Chips

- The production of advanced package in 2.5D TSV grows increasingly because of the growing needs of AI chips
- 3D TSV is under mass production, we not only improved our quality, but also increase our productivity, we estimate the needs will over hundred in five years

Auto oven

The new strategy of advanced package technology : high cleanliness surround radiant furnace

Carrier Bonder

2020~2021 Industrial Technology Opportunity in PCB

- IC substrate and HDI factory are continuously growing
- 5G server board
- Mini Led substrate is going to mass production

The number of factories of IC substrate and HDI are growing

- IC substrate/Substrate-Like PCB and HDI advanced equipment packaging
- The needs of ABF process equipment is continuously growing

Ultra-thin plate high-order laminating machine

Multi-chamber vacuum laminator (ABF)

ABF Mylar Peeler

5G server board

- The need of 5G cell site and cloud generator room is increasing
- Developing LCP market positively

Auto UV LED Exposure

RTR UV LED Exposure

RTR Auto Laminator

Mini Led substrate step into mass production

Along with the smart phone start to take mini LED for backlight function, making the amount of demand larger

Auto Vaccum laminator

Ultra-thin plate high-order laminating machine

Auto Mylar Peeler

TCF 創峰

TOP CREATION

Mature product high market share

- 5G communication, high frequency and high speed
- Automotive electronics, reliability
- FPC market, thin and fine
- Industrial transformation and expansion, Industry 4.0

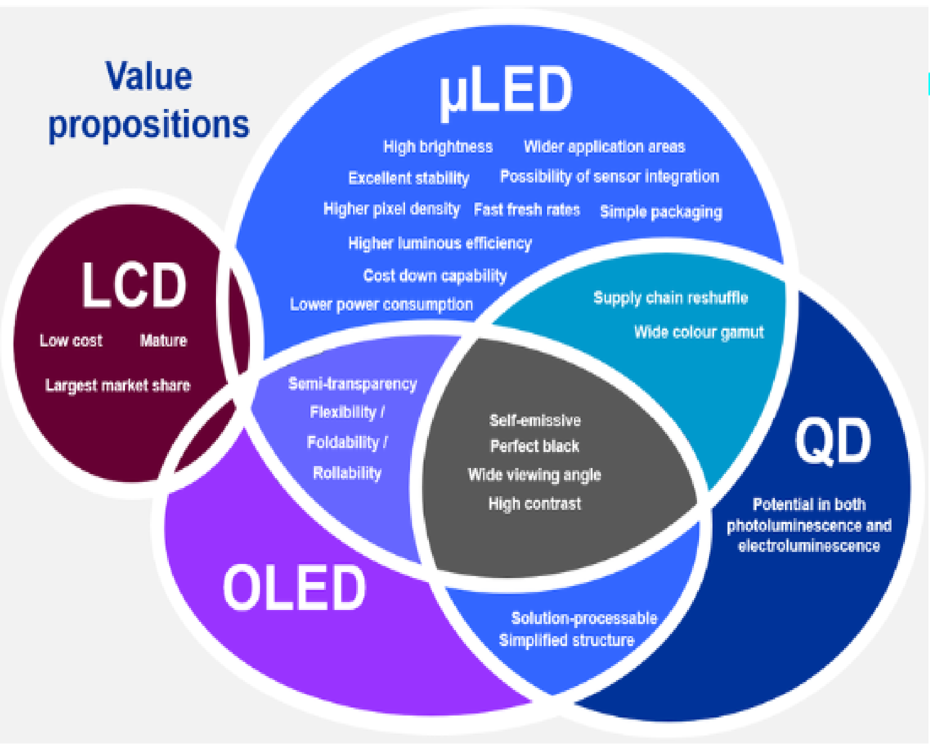
The usage of 5G make the industry growing

IC Substrate ultra thin board equipment promotion

- Optimize the vertical equipment、commercialize marketing

2020~2021 FPD industry and the opportunity

- G10.5、G8.6 TFT/OLED expansion demand in China
- High in-vehicle mode applied for big size(3D nurb)
- Mini LED/Micro LED
- The needs of E-sport FPD boost the high class process



Value propositions of various display technologies. Source: IDTechEx

In-vehicle panel curing, aging, laminating

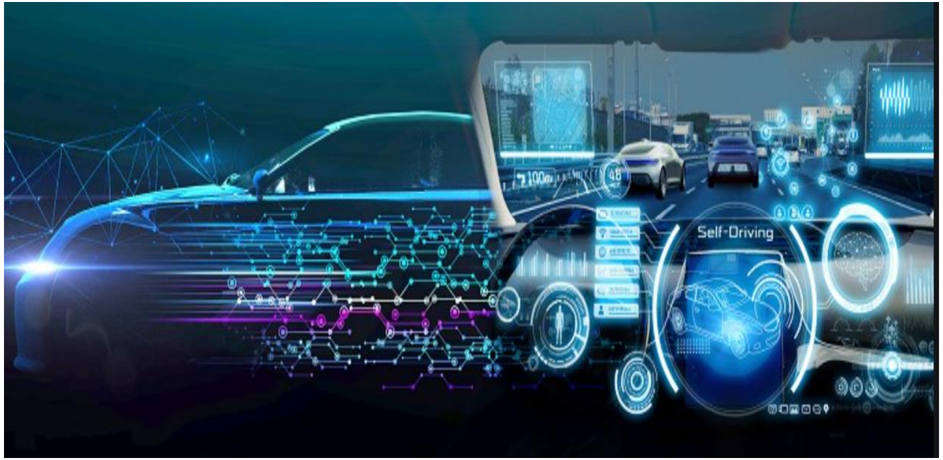
- Taiwan’s in-vehicle board expands production, the needs of revising machine is growing
- Q2 I company ordered in-vehicle panel mode automatic process, Q3 H company ordered in-vehicle panel aging process. We’ve earned the exclusive order from the car factory.
- 2020/Q4 laminator technology import In-Vehicle panel bonder process

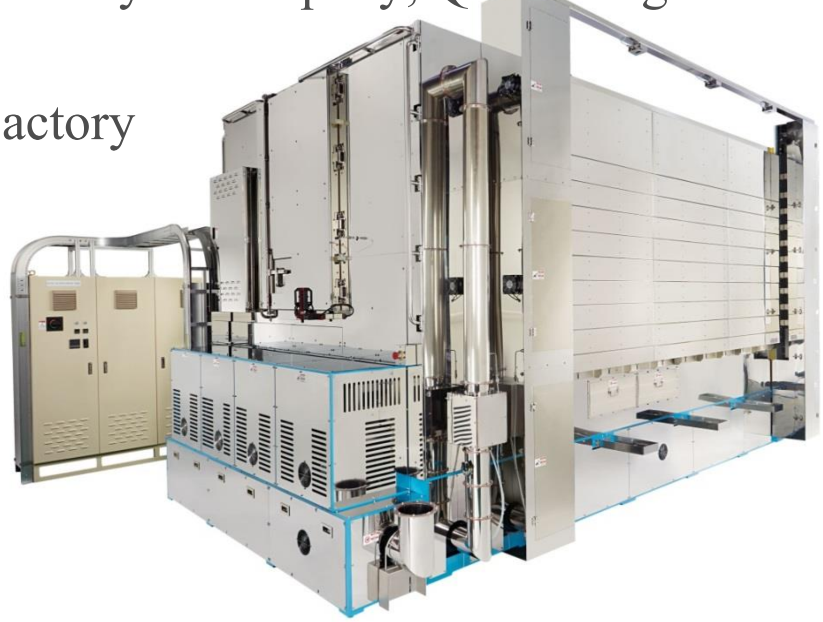
In-Vehicle
Panel Aging System

In-Vehicle
Panel Laminator

3D curved protective glass for car

- Panel for cars with high protective glasses for Anti-glare and Anti-fingerprint Coating baking line
- Handed to the Japan’s well known glasses factory A company, Q3~testing for mass production process
- Talking about collaboration with China’s Factory





Mini /Micro LED apply

- Mini LED backlight apply gradually play a role in high class panel
- Importing Micro LED control line, for the preparation of mass production
- Glass panel process import baking、UV、Plasma equipment on apply products
- Q2 earned Epitaxial factory apply plasma on mini LED desmear equipment order
- Q4 Heat Treatment Furnace Industrial Oven import Micro LED RD line

Needs of E-sport panel

The delivery of e-sport LCD in 2020 is about 12,200,000

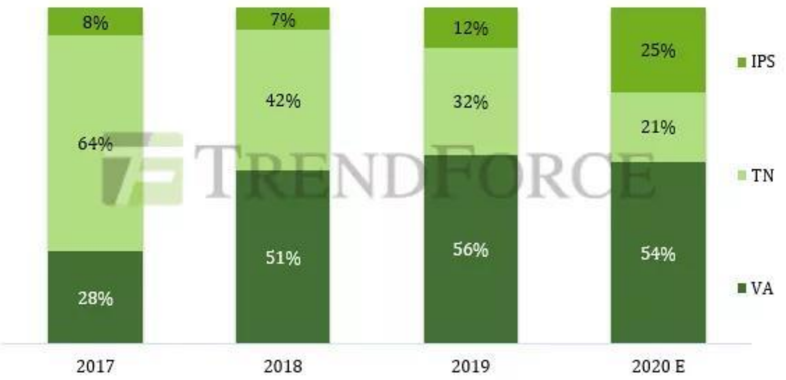
The amount increased 37% in 2019

IPS、VA technology is developing, so do the demand

年度	2020年		2024年		年複合成長率（%）
產品	出貨量（萬台）	ASP（美元）	出貨量（萬台）	ASP（美元）	
電競桌機	1,480	699	1,580	671	1.6
電競螢幕	1,240	348	1,600	341	6.4
電競筆電	2,230	967	3,020	955	7.9
總量	4,960	–	6,190	–	5.7

資料來源：IDC，2020/9　整理：翁毓嵐

图一、2017年~2020年电竞液晶显示器面板类型比例



Source: TrendForce, Jul. 2020

Q4/the expactation in 2020

- G2C organization create the value of vertical integration
- Advanced packaging continuously absorbing OEM T Factory, and Packaging factory A CapEx
- IC substrate、mini LED apply continuously expanding, absorbed the investment from Taiwan
- The demand of HDI server board is rising, the CapEx of equipment is growing
- G10.5, G8.6 expansion demand in China
- The high class vehicle mode apply for big size, next wave of panel investment
- The possibility of Micro LED of mass production, the opportunity of display technology

Q & A

Thank You